

SNxAHCT74 Dual Positive-Edge-Triggered D-Type Flip-Flops With Clear And Preset

1 Features

- Operating range of 4.5 V to 5.5 V
- Low power consumption, 10- μ A maximum I_{CC}
- ± 8 -mA output drive at 5 V
- Inputs are TTL-voltage compatible
- Latch-up performance exceeds 250 mA per JESD 17

2 Applications

- [Convert a momentary switch to a toggle switch](#)
- [Hold a signal during controller reset](#)
- [Input slow edge-rate signals](#)
- [Operate in noisy environments](#)
- Divide a clock signal by two

3 Description

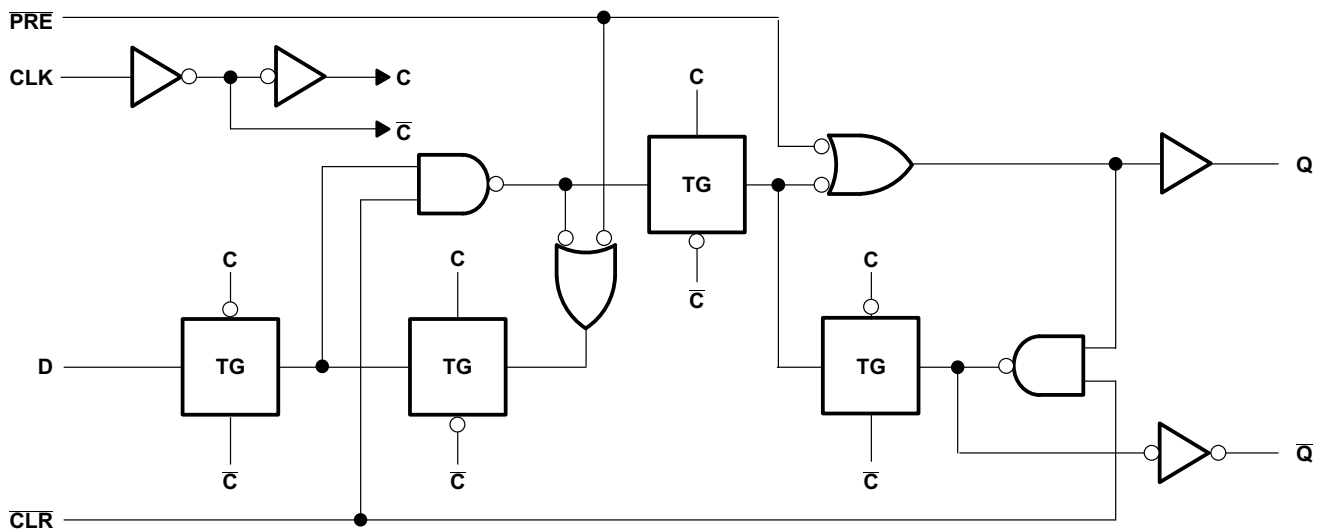
The 'AHCT74 dual positive-edge-triggered devices are D-type flip-flops.

A low level at the preset (\overline{PRE}) or clear (\overline{CLR}) inputs sets or resets the outputs, regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

Device Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾	BODY SIZE (NOM) ⁽³⁾
SN54AHCT74	J (CDIP, 14)	21.3 mm \times 7.6 mm	19.56 mm \times 6.67 mm
	W (CFP, 14)	13.1 mm \times 6.92 mm	13.1 mm \times 6.92 mm
	FK (LCCC, 20)	8.9 mm \times 8.9 mm	8.9 mm \times 8.9 mm
SN74AHCT74	N (PDIP, 14)	19.3 mm \times 8 mm	19.3 mm \times 6.35 mm
	D (SOIC, 14)	8.7 mm \times 6 mm	8.7 mm \times 3.91 mm
	NS (SOP, 14)	10.3 mm \times 7.8 mm	10.3 mm \times 5.3 mm
	DB (SSOP, 14)	6.2 mm \times 7.8 mm	6.2 mm \times 5.3 mm
	PW (TSSOP, 14)	5 mm \times 6.4 mm	5 mm \times 4.4 mm
	DGV (TVSOP, 14)	3.6 mm \times 6.4 mm	3.6 mm \times 4.4 mm
	RGY (VQFN, 14)	3.5 mm \times 3.5 mm	3.50 mm \times 3.50 mm
	BQA (WQFN, 14)	3 mm \times 2.5 mm	3.00 mm \times 2.50 mm

- (1) For all available packages, see the orderable addendum at the end of the data sheet.
- (2) The package size (length \times width) is a nominal value and includes pins, where applicable.
- (3) The body size (length \times width) is a nominal value and does not include pins.



Logic Diagram, Each Flip-Flop (Positive Logic)



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4 Revision History

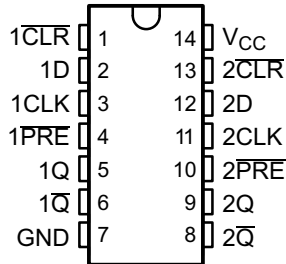
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision Q (July 2023) to Revision R (October 2023)	Page
• Updated title and format of <i>Device Information</i> table.....	1
• Updated R θ JA values: D = 86 to 124.5, all values in °C/W	5

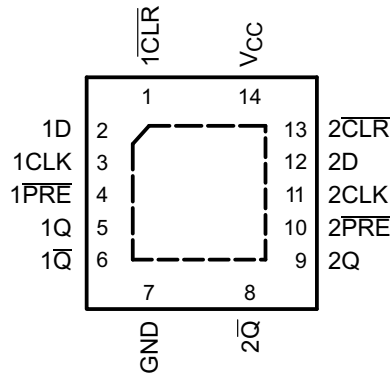
Changes from Revision P (May 2023) to Revision Q (July 2023)	Page
• Updated thermal values for PW package from R θ JA = 113 to 147.7, all values in °C/W.....	5

5 Pin Configuration and Functions

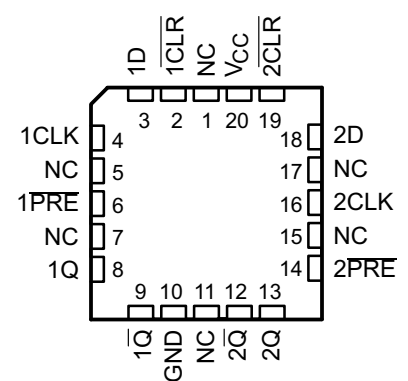
SN54AHCT74 . . . J or W PACKAGE
SN74AHCT74 . . . D, DB, DGV, N, NS,
OR PW PACKAGE
(TOP VIEW)



SN74AHCT74 . . . RGY PACKAGE
(TOP VIEW)



SN54AHCT74 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

Figure 5-1. Title

Table 5-1. Pin Functions

NAME	PIN				TYPE ⁽¹⁾	DESCRIPTION
	SN74AHCT74		SN54AHCT74			
	D, DB, DGV, N, NS, PW	RGY, BQA	J, W	FK		
1CLR	1	1	1	2	I	1A Input
1D	2	2	2	3	I	1B Input
1CLK	3	3	3	4	O	1Y Output
1PRE	4	4	4	6	I	2A Input
1Q	5	5	5	8	I	2B Input
1Q̄	6	6	6	9	O	2Y Output
2Q̄	8	8	8	12	O	3Y Output
2Q	9	9	9	13	I	3A Input
2PRE	10	10	10	14	I	3B Input
2CLK	11	11	11	16	O	4Y Output
2D	12	12	12	18	I	4A Input
2CLR	13	13	13	19	I	4B Input
GND	7	7	7	10	—	Ground Pin
NC	—	—	—	1, 5, 7, 11, 15, 17	—	No Connection
V _{CC}	14	14	14	20	—	Power Pin
Thermal Pad	—	PAD	—	—	—	Thermal Pad

(1) Signal Types: I = Input, O = Output, I/O = Input or Output.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	-0.5	7	V
V _I ⁽²⁾	Input voltage range	-0.5	7	V
V _O ⁽²⁾	Output voltage range	-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current, (V _I < 0)		-20	mA
I _{OK}	Output clamp current (V _O < 0 or V _O > V _{CC})		±20	mA
I _O	Continuous output current (V _O = 0 to V _{CC})		±25	mA
Continuous current through V _{CC} or GND			±50	mA
T _{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

6.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000
		Charged device model (CDM), per ANSI/ESDA/JEDEC JS-002 ⁽²⁾	±1000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		SN54AHCT74		SN74AHCT74		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V _{IH}	High-level input voltage	2		2		V
V _{IL}	Low-level Input voltage		0.8		0.8	V
V _I	Input voltage	0	5.5	0	5.5	V
V _O	Output voltage	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current		-8		-8	mA
I _{OL}	Low-level output current		8		8	mA
Δt/Δv	Input Transition rise or fall rate		20		20	ns/V
T _A	Operating free-air temperature	-55	125	-40	125	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

6.4 Thermal Information

THERMAL METRIC ¹	SNx4AHCT74								UNIT
	D	DB	DGV	N	NS	PW	RGY	BQA	
	14 PINS								
R _{θJA} Junction-to-ambient thermal resistance	124.5	96	127	80	76	147.7	47	88.3	°C/W

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report.

6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C		T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		T _A = -40°C TO 125°C		UNIT
					SN54AHCT74		SN74AHCT74		Recommended		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	
V _{OH}	I _{OH} = -50 μA	4.5 V	4.4	4.5	4.4		4.4		4.4		V
	I _{OH} = -8 mA		3.94		3.8		3.8		3.8		
V _{OL}	I _{OL} = 50 μA	4.5 V			0.1		0.1		0.1		V
	I _{OH} = 8 mA				0.36		0.44		0.44		
I _I	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1 ⁽¹⁾		±1		μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			2		20		20		μA
ΔI _{CC}	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			1.35		1.5		1.5		mA
C _i	V _I = V _{CC} or GND	5 V			2		10		10		pF

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

6.6 Timing Requirements

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see [Section 6.6](#))

PARAMETER		T _A = 25°C		T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		T _A = -40°C TO 125°C		UNIT
				SN54AHCT74		SN54AHCT74		Recommended		
		TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration	PRE or CLR low	5		5		5		5	ns
		CLK	5		5		5		5	
t _{su}	Setup time before CLK↑	Data	5		5		5		5	ns
		PRE or CLR inactive	3.5		3.5		3.5		3.5	
t _h	Hold time, data after CLK↑		0		0		0		0	ns

6.7 Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see [Figure 7-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		T _A = -40°C TO 125°C		UNIT
							SN54AHCT74		SN54AHCT74		Recommended		
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}			C _L = 15 pF	100 ⁽¹⁾	160 ⁽¹⁾		90		80		80	ns	
			C _L = 50 pF	80	140		65		65		65		

SN54AHCT74, SN74AHCT74

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 over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 7-1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			$T_A = -55^\circ\text{C TO } 125^\circ\text{C}$		$T_A = -40^\circ\text{C TO } 85^\circ\text{C}$		$T_A = -40^\circ\text{C TO } 125^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	Recommended		
											MIN	MAX	
t_{PLH}	PRE or CLR	Q or \bar{Q}	$C_L = 15\text{ pF}$	7.6 ⁽¹⁾	10.4 ⁽¹⁾	1 ⁽¹⁾	12 ⁽¹⁾	1	12	1	12	ns	
t_{PHL}				7.6 ⁽¹⁾	10.4 ⁽¹⁾	1 ⁽¹⁾	12 ⁽¹⁾	1	12	1	12		
t_{PLH}	CLK	Q or \bar{Q}	$C_L = 15\text{ pF}$	5.8 ⁽¹⁾	7.8 ⁽¹⁾	1 ⁽¹⁾	9 ⁽¹⁾	1	9	1	9.0	ns	
t_{PHL}				5.8 ⁽¹⁾	7.8 ⁽¹⁾	1 ⁽¹⁾	9 ⁽¹⁾	1	9	1	9.0		
t_{PLH}	PRE or CLR	Q or \bar{Q}	$C_L = 50\text{ pF}$	8.1	11.4	1	13	1	13	1	13	ns	
t_{PHL}				8.1	11.4	1	13	1	13	1	13		
t_{PLH}	CLK	Q or \bar{Q}	$C_L = 50\text{ pF}$	6.3	8.8	1	10	1	10	1	10	ns	
t_{PHL}				6.3	8.8	1	10	1	10	1	10		

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

6.8 Noise Characteristics

 $V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ ⁽¹⁾

PARAMETER		SN54AHCT74		UNIT
		MIN	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}	0.8		V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}	-0.8		V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}	4		V
$V_{IH(D)}$	High-level dynamic input voltage	2		V
$V_{IL(D)}$	Low-level dynamic input voltage	0.8		V

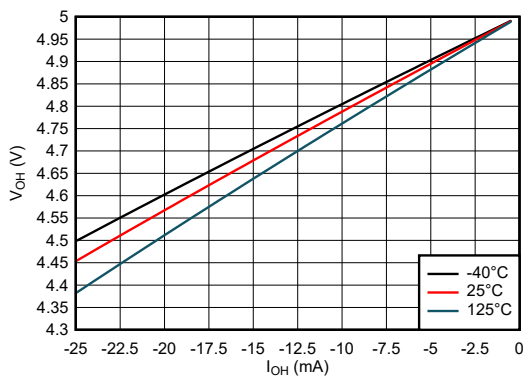
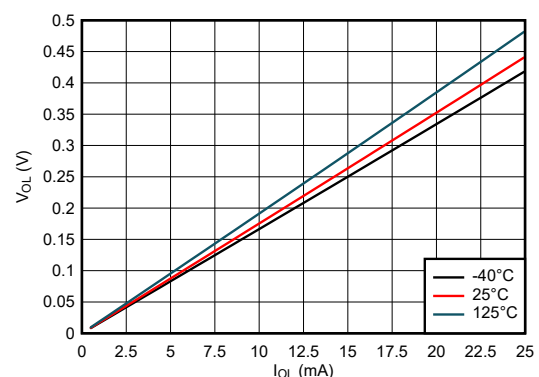
(1) Characteristics are for surface-mount packages only.

6.9 Operating Characteristics

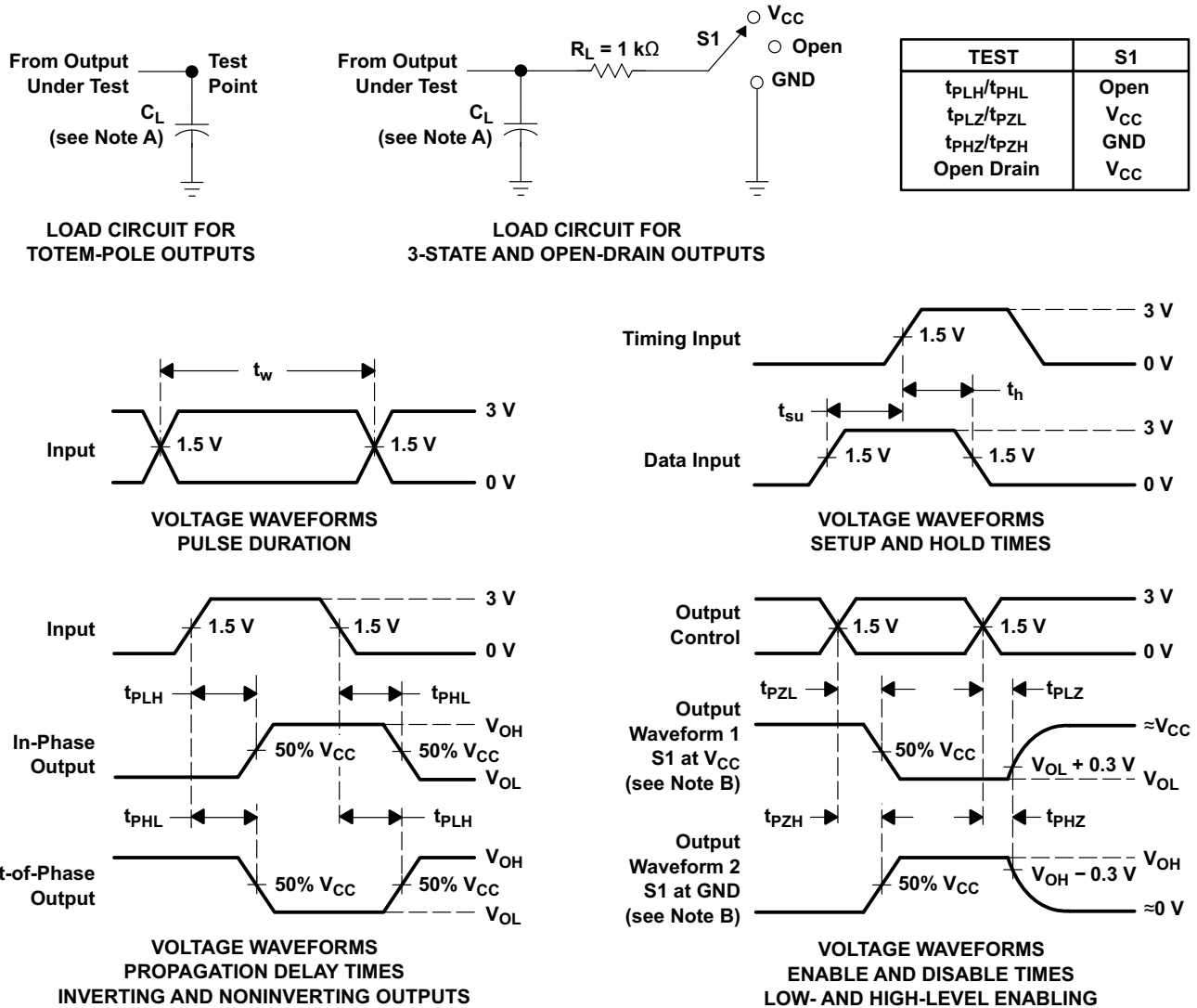
 $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd}	No load, $f = 1\text{ MHz}$	32	pF

6.10 Typical Characteristics

 $T_A = 25^\circ\text{C}$ (unless otherwise noted)

Figure 6-1. Output Voltage vs Current in HIGH State; 5-V Supply

Figure 6-2. Output Voltage vs Current in LOW State; 5-V Supply

7 Parameter Measurement Information



- C_L includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r \leq 3$ ns, $t_f \leq 3$ ns.
- The outputs are measured one at a time with one input transition per measurement.
- All parameters and waveforms are not applicable to all devices.

Figure 7-1. Load Circuit and Voltage Waveforms

8.3.2 Balanced CMOS Push-Pull Outputs

This device includes balanced CMOS push-pull outputs. The term *balanced* indicates that the device can sink and source similar currents. The drive capability of this device may create fast edges into light loads, so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. It is important for the output power of the device to be limited to avoid damage due to overcurrent. The electrical and thermal limits defined in the *Absolute Maximum Ratings* must be followed at all times.

Unused push-pull CMOS outputs should be left disconnected.

8.3.3 Clamp Diode Structure

As [Figure 8-2](#) shows, the outputs to this device have both positive and negative clamping diodes, and the inputs to this device have negative clamping diodes only.

CAUTION

Voltages beyond the values specified in the *Absolute Maximum Ratings* table can cause damage to the device. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

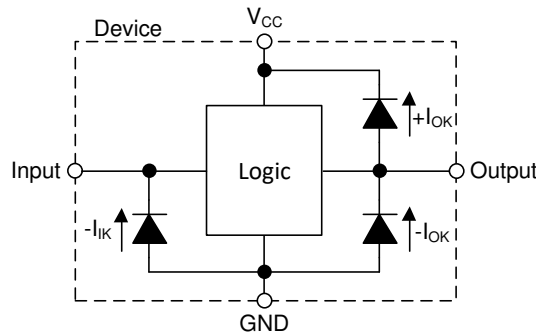


Figure 8-2. Electrical Placement of Clamping Diodes for Each Input and Output

8.4 Device Functional Modes

Table 8-1. Functional Table (Each Flip-Flop)

INPUTS				OUTPUT	
PRE	CLR	CLK	D	Q	\bar{Q}
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H ⁽¹⁾	H ⁽¹⁾
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q ₀	\bar{Q}_0

(1) This configuration is non-stable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

9 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

9.1 Application Information

Toggle switches are typically large, mechanically complex and relatively expensive. It is desirable to use a momentary switch instead because they are small, mechanically simple and low cost. Some systems require a toggle switch's functionality but are space or cost constrained and must use a momentary switch instead. External Schmitt-trigger buffers are used to remove noisy inputs into the (CLK) and (D) inputs.

If the data input (D) of the SNx4AHCT74 is tied to the inverted output (\overline{Q}), then each clock pulse will cause the value at the output (Q) to toggle. The momentary switch can be debounced and directly connected to the clock input (CLK) to toggle the output.

9.2 Typical Application

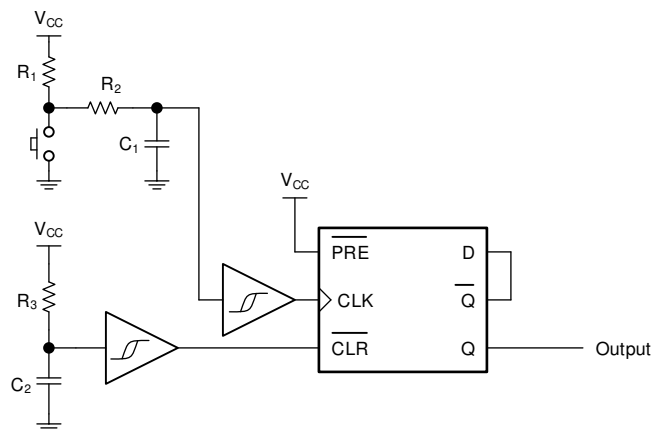


Figure 9-1. Typical Application Block Diagram

9.2.1 Design Requirements

9.2.1.1 Input Considerations

Input signals must cross to be considered a logic LOW, and to be considered a logic HIGH. Do not exceed the maximum input voltage range found in the *Absolute Maximum Ratings*.

Unused inputs must be terminated to either V_{CC} or ground. The unused inputs can be directly terminated if the input is completely unused, or they can be connected with a pull-up or pull-down resistor if the input will be used sometimes, but not always. A pull-up resistor is used for a default state of HIGH, and a pull-down resistor is used for a default state of LOW. The drive current of the controller, leakage current into the SNx4AHCT74 (as specified in the *Electrical Characteristics*), and the desired input transition rate limits the resistor size. A 10-k Ω resistor value is often used due to these factors.

Refer to the *Feature Description* section for additional information regarding the inputs for this device.

9.2.1.2 Output Considerations

The ground voltage is used to produce the output LOW voltage. Sinking current into the output will increase the output voltage as specified by the V_{OL} specification in the *Electrical Characteristics*.

Unused outputs can be left floating. Do not connect outputs directly to V_{CC} or ground.

Refer to the *Feature Description* section for additional information regarding the outputs for this device.

9.2.1.3 Power Considerations

Ensure the desired supply voltage is within the range specified in the *Recommended Operating Conditions*. The supply voltage sets the electrical characteristics of the device as described in the *Electrical Characteristics* section.

The positive voltage supply must be capable of sourcing current equal to the maximum static supply current, I_{CC} , listed in the *Electrical Characteristics*, and any transient current required for switching.

The ground must be capable of sinking current equal to the total current to be sunk by all outputs of the SNx4AHCT74 plus the maximum supply current, I_{CC} , listed in the *Electrical Characteristics*, and any transient current required for switching. The logic device can only sink as much current that can be sunk into its ground connection. Be sure to not exceed the maximum total current through GND listed in the *Absolute Maximum Ratings*.

The SNx4AHCT74 can drive a load with a total capacitance less than or equal to 50 pF while still meeting all of the data sheet specifications. Larger capacitive loads can be applied; however, it is not recommended to exceed 50 pF.

The SNx4AHCT74 can drive a load with total resistance described by $R_L \geq V_O / I_O$, with the output voltage and current defined in the *Electrical Characteristics* table with V_{OL} . When outputting in the HIGH state, the output voltage in the equation is defined as the difference between the measured output voltage and the supply voltage at the V_{CC} pin.

Total power consumption can be calculated using the information provided in [CMOS Power Consumption and Cpd Calculation](#) application note.

Thermal increase can be calculated using the information provided in [Thermal Characteristics of Standard Linear and Logic \(SLL\) Packages and Devices](#) application note.

CAUTION

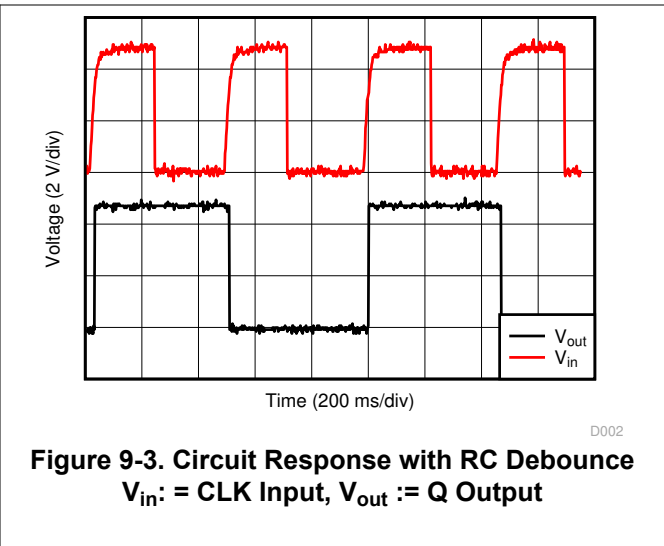
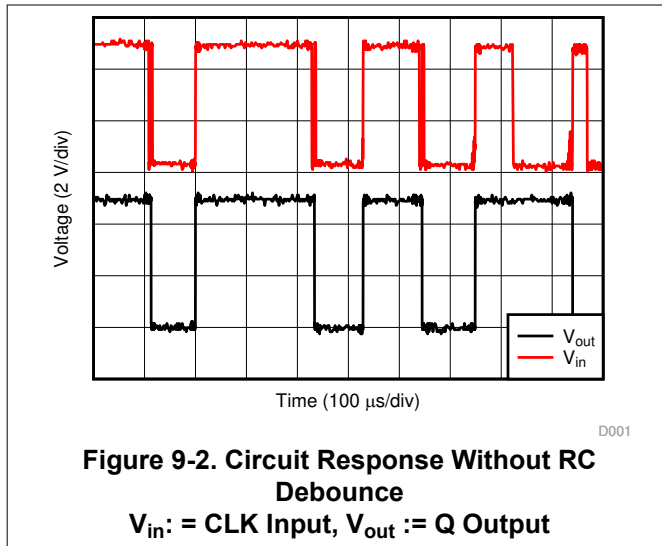
The maximum junction temperature, $T_{J(max)}$ listed in the *Absolute Maximum Ratings*, is an additional limitation to prevent damage to the device. Do not violate any values listed in the *Absolute Maximum Ratings*. These limits are provided to prevent damage to the device.

9.2.2 Detailed Design Procedure

1. Add a decoupling capacitor from V_{CC} to GND. The capacitor needs to be placed physically close to the device and electrically close to both the V_{CC} and GND pins. An example layout is shown in the *Layout* section.
2. Ensure the capacitive load at the output is ≤ 50 pF. This is not a hard limit; by design, however, it will optimize performance. This can be accomplished by providing short, appropriately sized traces from the SNx4AHCT74 to one or more of the receiving devices.
3. Ensure the resistive load at the output is larger than $(V_{CC} / I_{O(max)}) \Omega$. Doing this will prevent the maximum output current from the *Absolute Maximum Ratings* from being violated. Most CMOS inputs have a resistive load measured in $M\Omega$; much larger than the minimum calculated previously.
4. Thermal issues are rarely a concern for logic gates; the power consumption and thermal increase, however, can be calculated using the steps provided in the application report, [CMOS Power Consumption and Cpd Calculation](#).

9.2.3 Application Curves

Figure 9-2 shows an example of a single button press bouncing and causing the output to toggle multiple times. This will cause issues in the desired application. Figure 9-3 shows 4 button presses with an added debounce circuit, fixing the unwanted toggling and allowing for proper toggle switch operation.



9.3 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- μF capacitor is recommended for this device. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. The 0.1- μF and 1- μF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results, as shown in the following layout example.

9.4 Layout

9.4.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices, inputs must never be left floating. In many cases, functions or parts of functions of digital logic devices are unused (for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used). Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

9.4.1.1 Layout Example

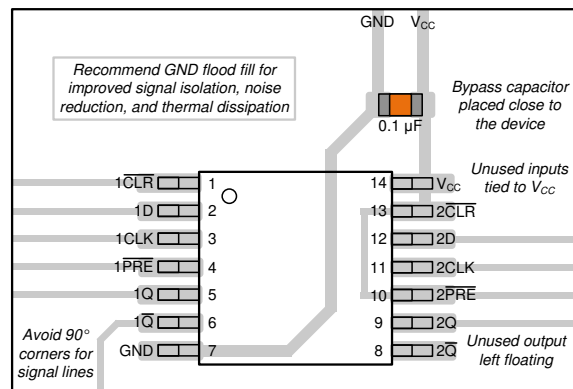


Figure 9-4. Layout Example of the SNx4AHCT74

10 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

10.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

10.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

10.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

10.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9686101Q2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9686101Q2A SNJ54AHCT74FK	Samples
5962-9686101QCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9686101QC A SNJ54AHCT74J	Samples
5962-9686101QDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9686101QD A SNJ54AHCT74W	Samples
SN74AHCT74BQAR	ACTIVE	WQFN	BQA	14	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT74	Samples
SN74AHCT74D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 125	AHCT74	
SN74AHCT74DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB74	Samples
SN74AHCT74DGVR	ACTIVE	TVSOP	DGV	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB74	Samples
SN74AHCT74DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT74	Samples
SN74AHCT74N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 125	SN74AHCT74N	Samples
SN74AHCT74NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT74	Samples
SN74AHCT74PW	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 125	HB74	
SN74AHCT74PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	HB74	Samples
SN74AHCT74PWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB74	Samples
SN74AHCT74RGYR	ACTIVE	VQFN	RGY	14	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HB74	Samples
SNJ54AHCT74FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9686101Q2A SNJ54AHCT74FK	Samples
SNJ54AHCT74J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9686101QC A SNJ54AHCT74J	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54AHCT74W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9686101QD A SNJ54AHCT74W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54AHCT74, SN74AHCT74 :

- Catalog : [SN74AHCT74](#)
- Enhanced Product : [SN74AHCT74-EP](#), [SN74AHCT74-EP](#)
- Military : [SN54AHCT74](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT74BQAR	WQFN	BQA	14	3000	180.0	12.4	2.8	3.3	1.1	4.0	12.0	Q1
SN74AHCT74DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74AHCT74DGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74AHCT74DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHCT74DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHCT74NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AHCT74PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHCT74PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHCT74RGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT74BQAR	WQFN	BQA	14	3000	210.0	185.0	35.0
SN74AHCT74DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74AHCT74DGVR	TVSOP	DGV	14	2000	356.0	356.0	35.0
SN74AHCT74DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74AHCT74DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74AHCT74NSR	SO	NS	14	2000	356.0	356.0	35.0
SN74AHCT74PWR	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74AHCT74PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74AHCT74RGYR	VQFN	RGY	14	3000	356.0	356.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9686101Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9686101QDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74AHCT74N	N	PDIP	14	25	506	13.97	11230	4.32
SN74AHCT74N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54AHCT74FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AHCT74W	W	CFP	14	25	506.98	26.16	6220	NA

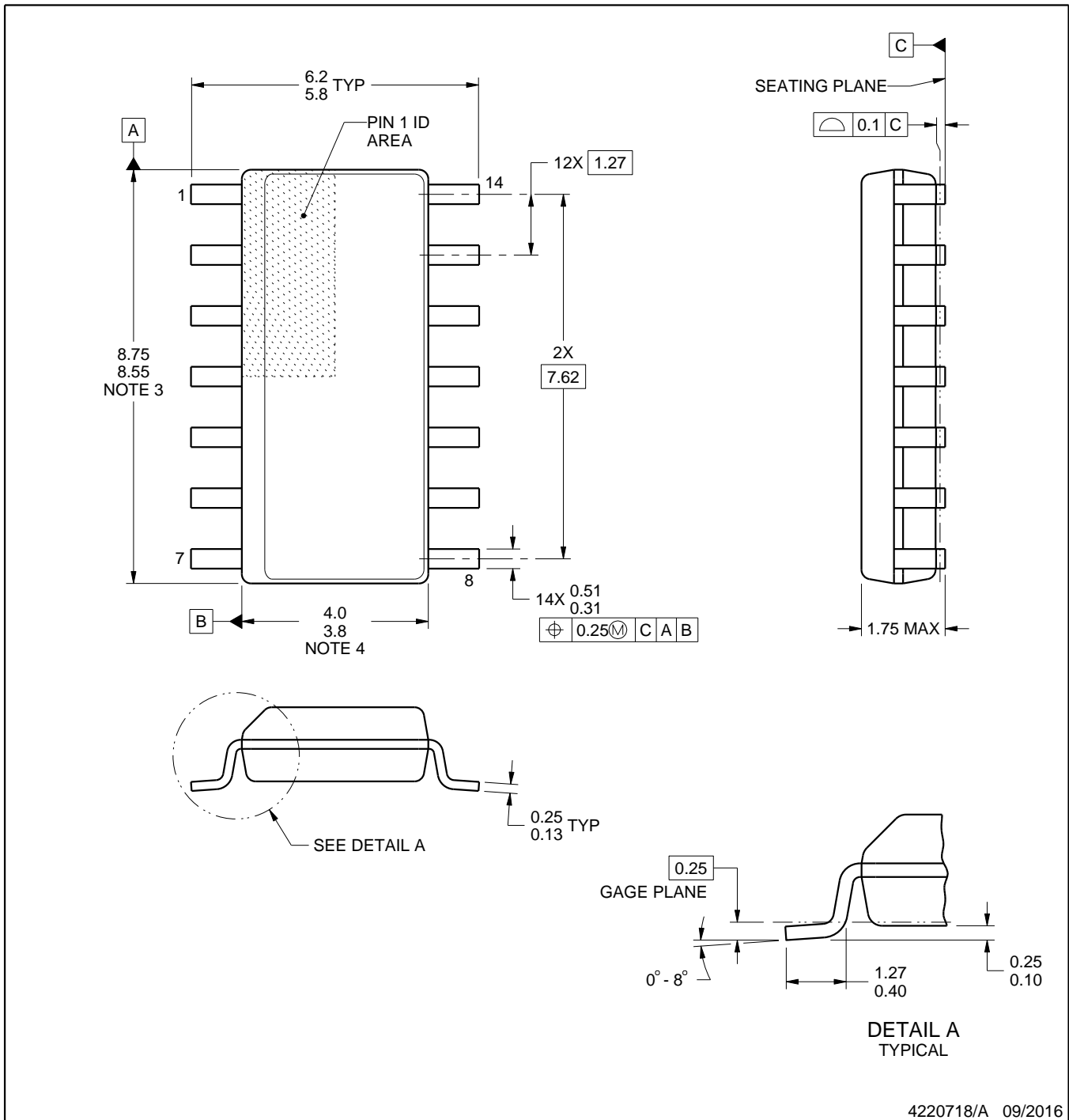
D0014A



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

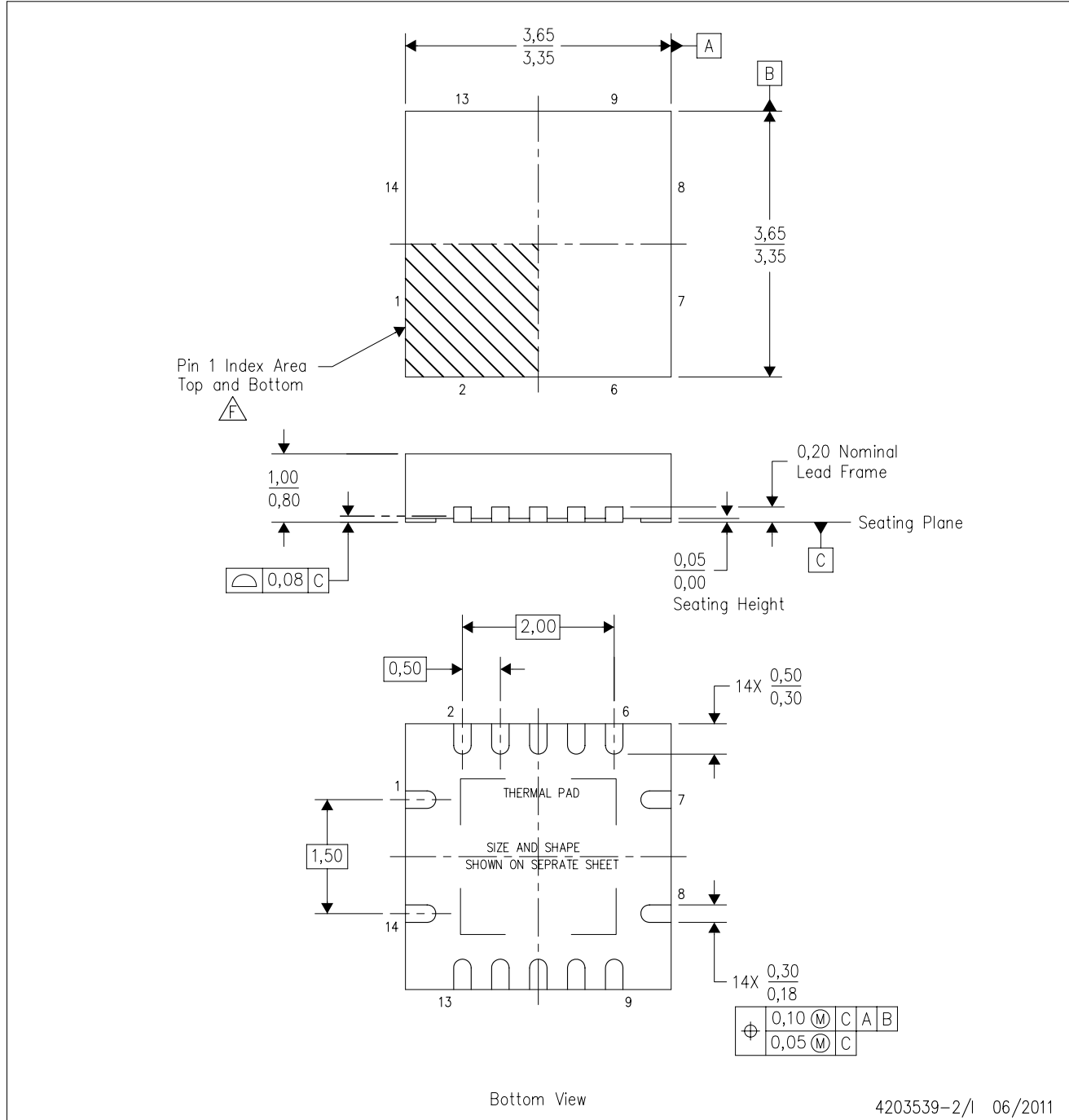
4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



4203539-2/1 06/2011

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - Package complies to JEDEC MO-241 variation BA.

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

Exposed Thermal Pad Dimensions

4206353-2/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



4208122-2/P 03/14

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

GENERIC PACKAGE VIEW

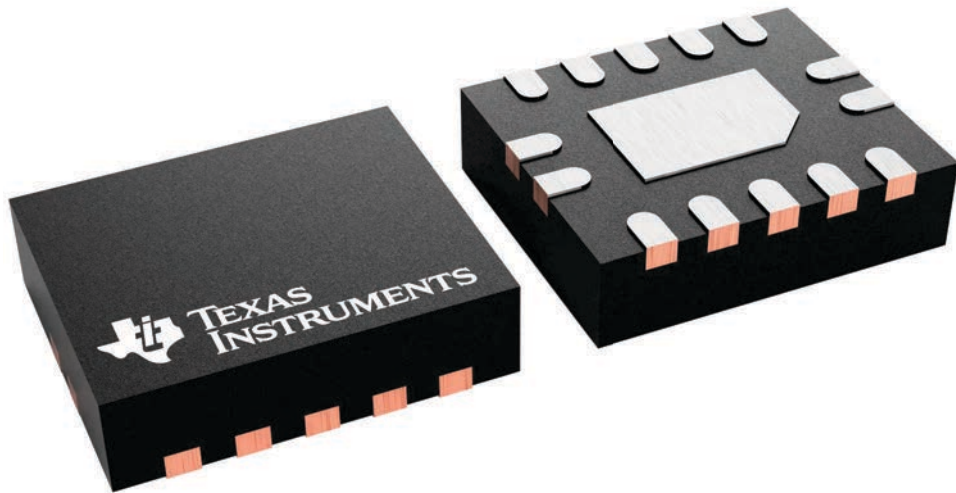
BQA 14

WQFN - 0.8 mm max height

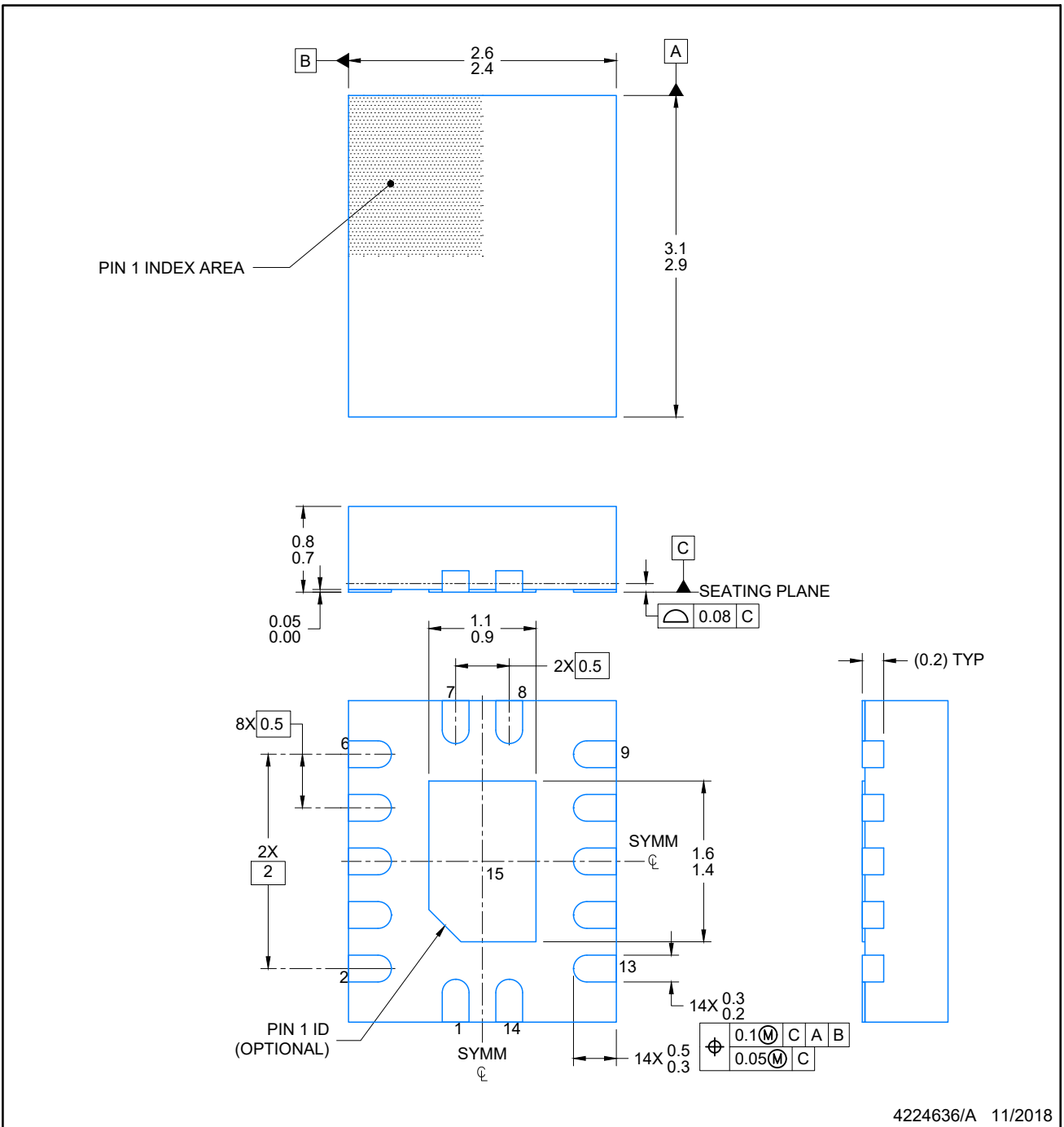
2.5 x 3, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4227145/A



4224636/A 11/2018

NOTES:

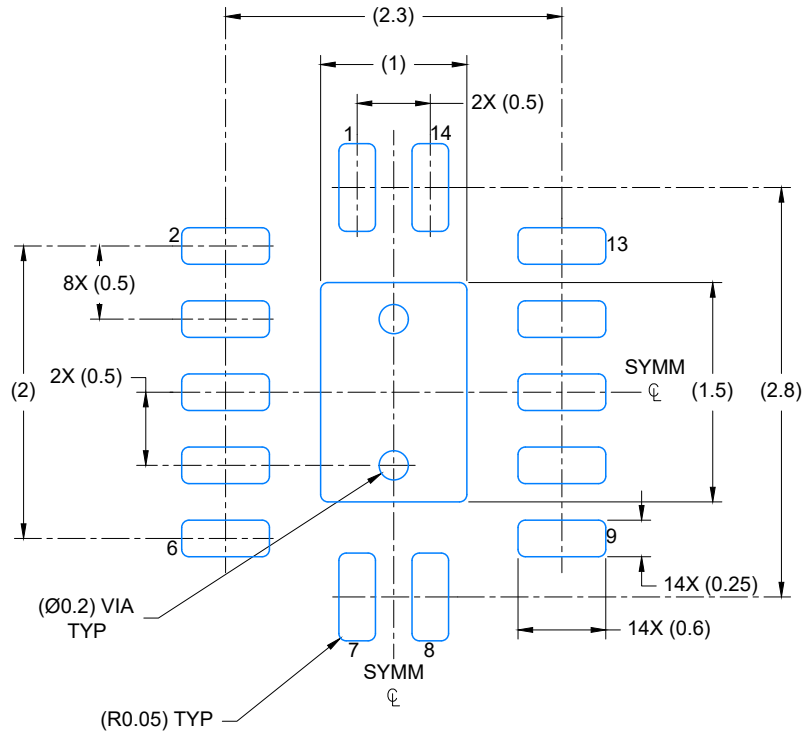
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

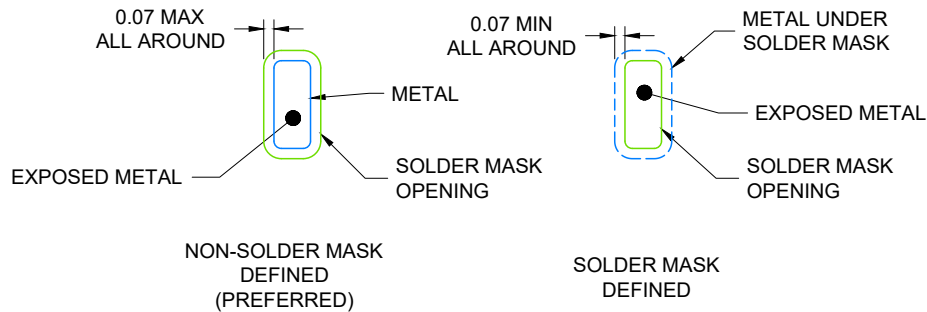
BQA0014A

WQFN - 0.8 mm max height

PLASTIC QUAD FLAT PACK-NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



4224636/A 11/2018

NOTES: (continued)

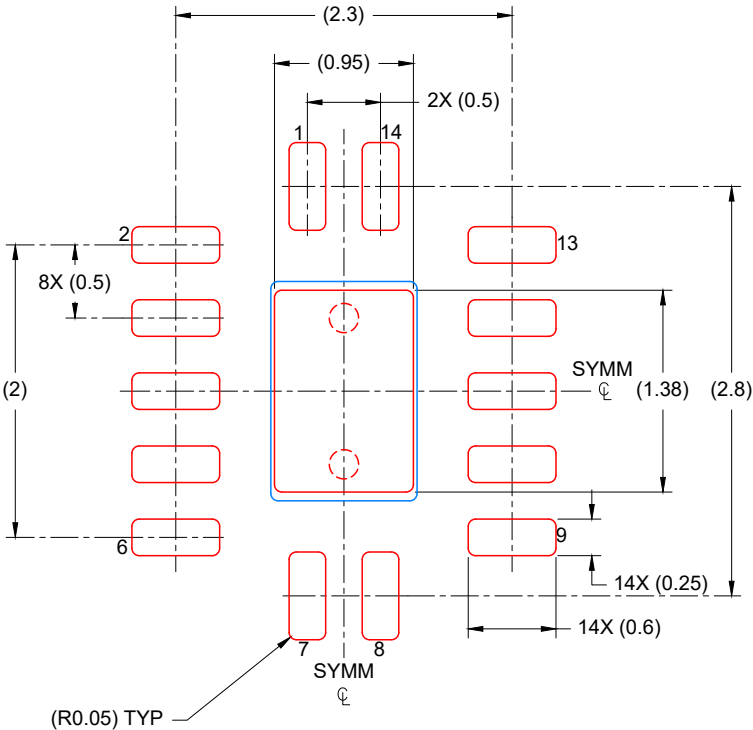
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

BQA0014A

WQFN - 0.8 mm max height

PLASTIC QUAD FLAT PACK-NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
88% PRINTED COVERAGE BY AREA
SCALE: 20X

4224636/A 11/2018

NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DB0014A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220762/A 05/2024

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

GENERIC PACKAGE VIEW

FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4229370VA\

J 14

GENERIC PACKAGE VIEW
CDIP - 5.08 mm max height
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



4214771/A 05/2017

N (R-PDIP-T**)

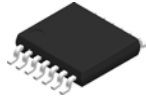
PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

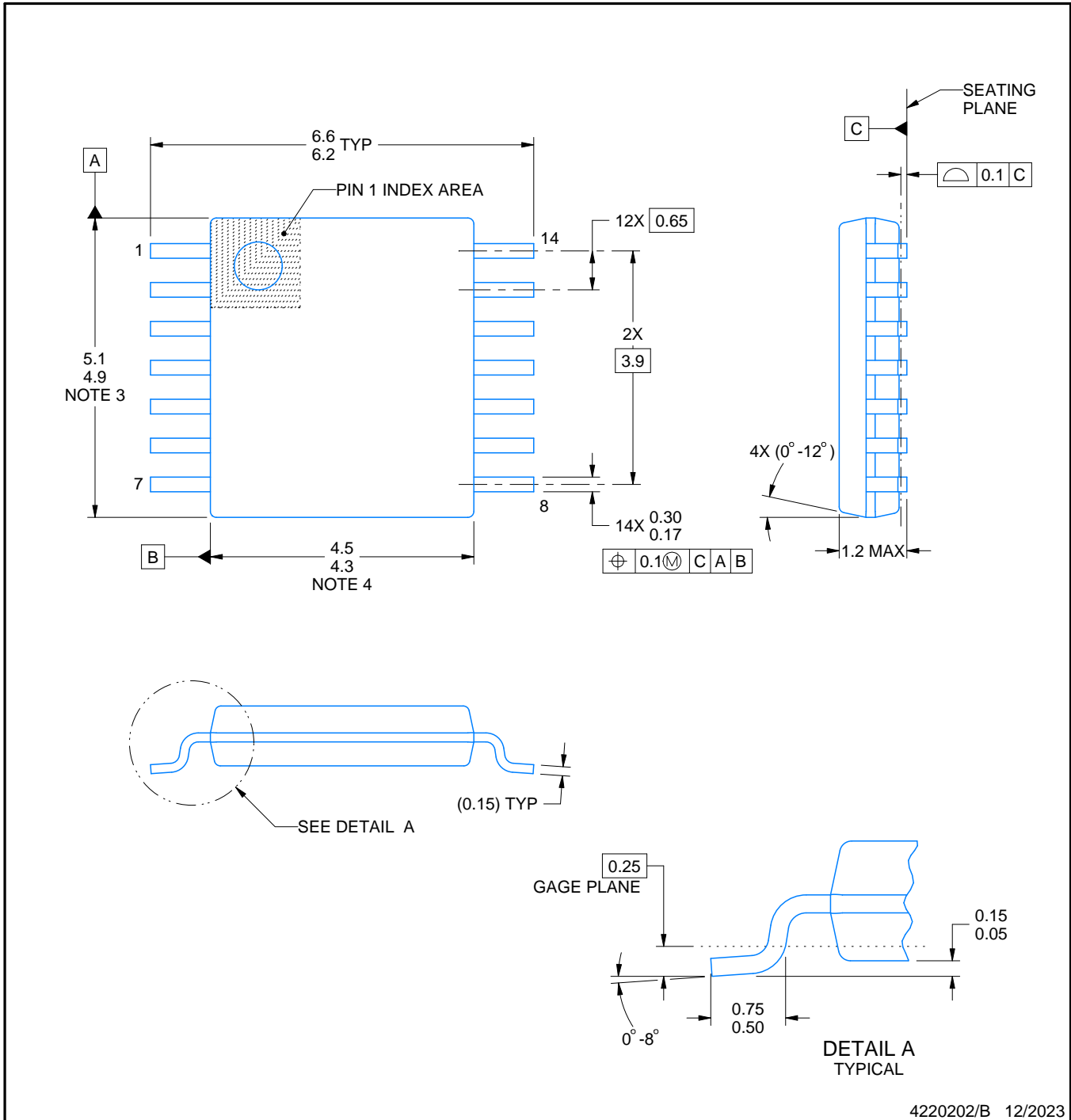
PW0014A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220202/B 12/2023

NOTES:

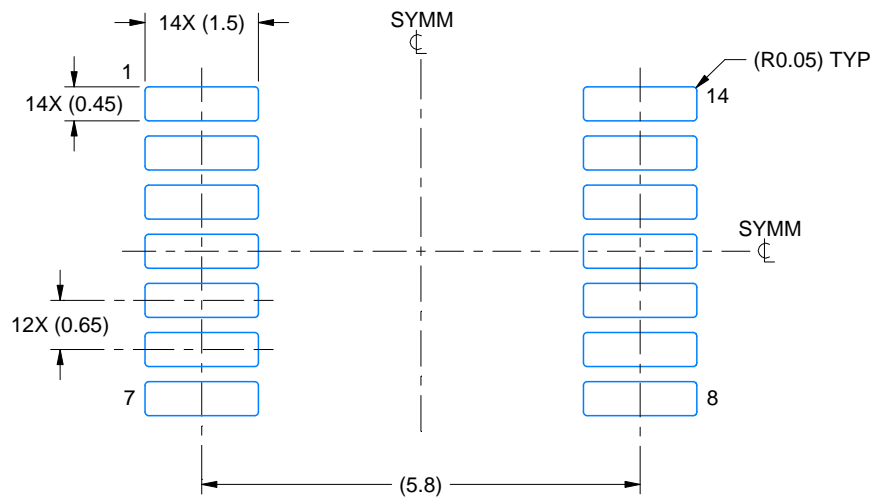
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

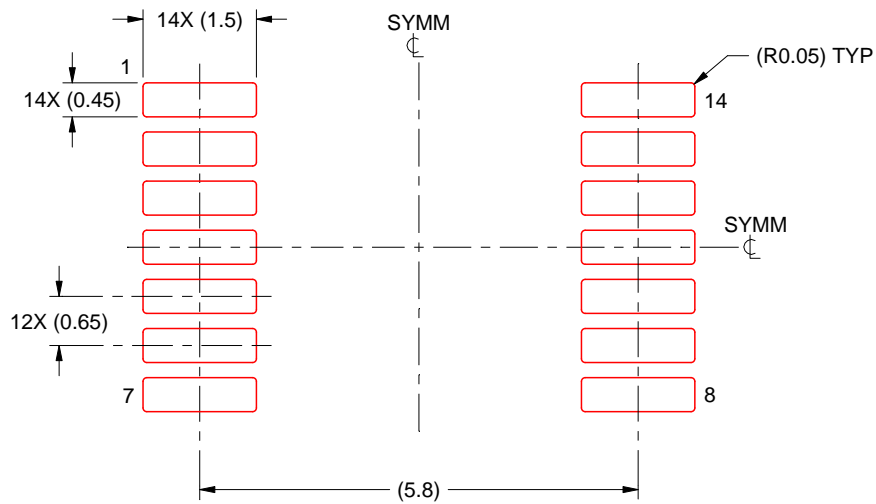
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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